



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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# PRINTED CIRCUIT BOARDS

01

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 241 FR4 70 L141.70 P18

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_241\_FR4\_70\_L141.70\_p18

Layers	in $\mu$	Material	Build-Up	Assembly	
Layer-1	70 $\mu$	Copper		A1	
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
Layer-2	70 $\mu$	Copper			B
	1410 $\mu$	L-FR4			
Layer-3	70 $\mu$	Copper			
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
Layer-99	70 $\mu$	Copper			

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